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SOLUTION GUIDE

RF Solutions for Aerospace and Defense



Table of Contents

03 **RF Connectivity Solutions for Aerospace and Defense Innovation**

04 **Meeting Evolving Mission Demands in Aerospace and Defense**

05 **Challenges and Opportunities in Aerospace and Defense RF Systems**

- Accelerating Qualification and Time-to-Field
- System-Level RF Integration Risk
- Mission Reliability in Harsh Environments
- Higher Frequencies and System Density

07 **RF Capabilities Required for Success in Aerospace and Defense**

- Accelerated Qualification and Standards Compliance
- Predictable RF Performance and Interoperability
- Reliable Operation in Mission-Critical Environments
- Integrated EMI/EMC Protection

11 **RF Innovation Across Aerospace and Defense Applications**

- Commercial Aerospace
- Defense
- Autonomous and Mobile Platforms
- Naval and Infrastructure Platforms
- Validation Systems

14 **Molex RF Solutions for Aerospace and Defense**

- RF Connectors
- RF Signal Conditioning and Power Management Solutions
- EMI/EMC Protection and Signal Integrity Solutions

19 **Aerospace and Defense RF Solution Selection Guide**

20 **Advancing the Next Generation of Aerospace and Defense RF Systems**

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RF CONNECTORS FOR AEROSPACE AND DEFENSE INNOVATION

Aerospace and defense platforms continue to grow more complex as systems push for higher frequencies, tighter packaging constraints and greater expectations for mission reliability. As modern architectures migrate toward these higher frequency bands and stricter size, weight and power (SWaP) constraints, the margin for error shrinks.

Engineering teams must balance ruggedization, EMI protection and interoperability without sacrificing time to field, making the selection of RF connectivity more crucial than ever.

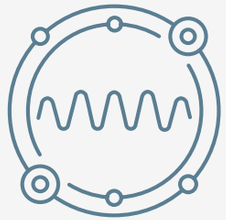
WHAT IS DRIVING RF TESTING INNOVATION?



Escalating RF Performance Gaps (40 to 65 GHz)



Stricter Qualification and Standards (MIL-SPEC, DO-160, VITA)



System-Level EMI/EMC and Signal Integrity Risks



Accelerated Time-to-Field Pressures





MEETING EVOLVING MISSION DEMANDS IN AEROSPACE AND DEFENSE

Aerospace and defense programs face compressed schedules while qualification expectations remain stringent. Engineers look for components that handle extreme frequencies, survive severe environmental stress and comply with strict military standards. Relying on mixed components from multiple suppliers complicates testing and increases the risk of late-stage failures that delay schedules. System designers need solutions that move connectivity upstream in the design process.

Engineered, end-to-end RF subsystems provide a distinct advantage over piece-part buying. Integrating high-frequency connectors, configurable cable assemblies, into a cohesive signal path eliminates integration guesswork. Combining high-performance RF technologies with standards-aligned, mission-ready solutions helps customers accelerate qualification, reduce integration risk and improve system performance in harsh environments.

CHALLENGES AND OPPORTUNITIES IN AEROSPACE AND DEFENSE RF SYSTEMS

Aerospace and defense platforms face a complex landscape of technical and regulatory hurdles. The push toward higher frequency bands in radar, SATCOM and electronic warfare systems, coupled with stricter export compliance requirements, adds further complexity. Engineering teams face the challenge of solving electrical, thermal, EMI and mechanical constraints as one unified system problem to prevent expensive redesigns.

ACCELERATING QUALIFICATION AND TIME-TO-FIELD

Validating mixed, discrete parts in-house multiplies test iterations against MIL-SPEC, DO-160 and VITA standards. These repeated qualification cycles delay time to field and increase overall program costs. Relying on multiple vendors for individual components adds significant integration overhead and obsolescence risk.

SYSTEM-LEVEL RF INTEGRATION RISK

Separately sourced connectors, attenuators and EMI mitigation solutions often interact unpredictably, creating impedance mismatches and resonance issues. These signal integrity surprises typically emerge late in the integration process, triggering costly board respins or shielding redesigns.



MISSION RELIABILITY IN HARSH ENVIRONMENTS

Aerospace and defense platforms operate in extreme conditions, exposing RF systems to severe temperature swings, shock, vibration and corrosion. Because of these harsh realities, meeting DO-160 Level IV transient standards and surviving these environments requires parts validated for system-level ruggedization, as component-level specifications alone often fall short. Additionally, high-power attenuators and terminations create thermal hotspots that degrade long-term reliability unless engineers account for them in early thermal design.





HIGHER FREQUENCIES AND SYSTEM DENSITY

The migration toward frequencies above 65 GHz exposes the limitations of legacy connectors and piece-part sourcing. These higher frequencies, combined with increased RF channel density, often lead to unexpected signal loss and failed link budgets.

At the same time, strict SWaP constraints force designers to use ultra-miniature footprints and tighter board-to-board spacing, which significantly increases mechanical and signal integrity complexity. Adding to this challenge, modern avionics and COTS-based modules increasingly mandate compliance with VITA and MIL standards. Relying on mixed, nonstandard interfaces creates severe interoperability risks and complicates system integration.

RF CAPABILITIES REQUIRED FOR SUCCESS IN AEROSPACE AND DEFENSE

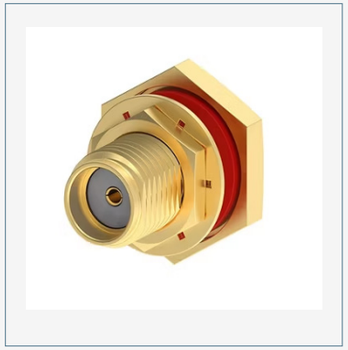
System designers can prevent late-stage redesigns and lengthy debug cycles by specifying pre-validated assemblies rather than sourcing discrete components. Consolidating vendors and requesting supplier-level environmental and qualification evidence up front reduces integration surprises, shortens design-in cycles and lowers lifecycle costs.

ACCELERATED QUALIFICATION AND STANDARDS COMPLIANCE

Validated RF solutions with documented MIL-SPEC and DO-160 performance data reduce in-house testing iterations and accelerate program acceptance. Specifying components with proven compliance helps engineering teams meet strict aerospace standards without adding schedule risk or increasing program overhead. Selecting pre-qualified interconnects and integrated EMI filtered products allows designers to focus on system-level performance rather than component-level troubleshooting.

FEATURED PRODUCTS

STANDARDS-ALIGNED RF INTERCONNECTS



SMA Connectors



TNC Connectors



EMI Filtered D-Subs

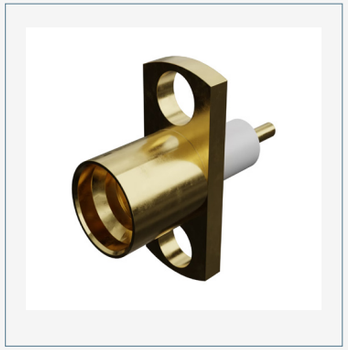


PREDICTABLE RF PERFORMANCE AND INTEROPERABILITY

Utilizing standardized, high-frequency interfaces in custom RF solutions supports mmWave applications and compact board real estate while maintaining strict signal integrity. Deploying components compliant with VITA and MIL-STD specifications prevents the interoperability risks associated with mixing nonstandard interfaces across subsystems. Configurable MIL-SPEC cable assemblies help engineering teams support multiple platform variants with minimal redesign, lowering non-recurring engineering (NRE) costs.

FEATURED PRODUCTS

HIGH-FREQUENCY MINIATURE SOLUTIONS



SMP Connectors



SMPM Connectors



RF Cable Assemblies





RELIABLE OPERATION IN MISSION-CRITICAL ENVIRONMENTS

Matching attenuators and terminations to the system power budget prevents thermal hotspots and reduces in-service power failures. Components validated for shock, vibration and extreme temperatures maintain mission reliability in the harshest operating conditions. End-to-end validated assemblies, such as circular EMI filter connectors, provide the transient immunity and lightning resilience needed to meet DO-160 Level IV standards.

FEATURED PRODUCTS

RUGGEDIZED SIGNAL CONDITIONING AND PROTECTION



Coaxial Terminators



Coaxial Attenuators



Circular EMI Filter Connectors

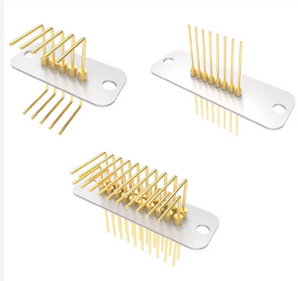


INTEGRATED EMI/EMC PROTECTION

Integrating EMI filtering directly into connector and cable choices reduces radiated susceptibility risks and prevents late-stage field fixes. Conventional EMI mitigation often underperforms at higher frequencies. Engineering EMI protection as a system-level solution addresses emissions early in the design lifecycle and helps teams avoid costly board respins.

FEATURED PRODUCTS

INTEGRATED EMI/EMC SOLUTIONS



EMI Filter Plates



EMI Filtered D-Subs



Circular EMI Filter Connectors

RF INNOVATION ACROSS AEROSPACE AND DEFENSE APPLICATIONS

A comprehensive RF portfolio covering diverse aerospace and defense applications helps engineering teams expedite supplier approval and streamline procurement. Grouping these technologies by operating environment allows designers to quickly identify the right RF components for their specific mission requirements.

COMMERCIAL AEROSPACE

Airborne platforms require ultra-miniature, lightweight RF interconnects that maintain signal integrity despite heavy vibration and rapid temperature cycling.

- **Wide-Body Aircraft:** High-density RF routing supports advanced passenger connectivity and complex avionics.
- **Narrow-Body Aircraft:** Lightweight, space-saving interconnects help reduce overall weight.
- **Electric Vertical Take-Off and Landing Aircraft (eVOTL):** EMI-shielded connectivity protects critical flight controls from internal electrical noise.





RF INNOVATION ACROSS AEROSPACE AND DEFENSE APPLICATIONS (CONTINUED)

DEFENSE

Mission-critical defense architectures depend on ruggedized, high-power RF solutions that deliver secure, interference-free communication and electronic warfare capabilities.

- **Military Aircraft:** Ruggedized RF paths secure high-speed tactical data links during combat operations.
- **Missile Defense:** Extreme shock and vibration resistance helps maintain precise targeting and telemetry data.
- **Military UAV:** Miniature RF solutions meet strict SWaP constraints during extended surveillance missions.
- **C5ISR:** High-frequency, interoperable connections deliver real-time battlefield intelligence across domains.
- **Soldier Systems:** Lightweight, durable interconnects keep wearable communication gear functioning in the field.
- **Ground Systems and Vehicles:** Heavy-duty, corrosion-resistant components survive harsh terrain and operations in extreme weather.
- **Military Marine:** Sealed, salt-spray-resistant RF solutions protect vital naval communications.

RF INNOVATION ACROSS AEROSPACE AND DEFENSE APPLICATIONS (CONTINUED)

Standardizing RF interfaces across diverse platforms allows teams to reuse validated subsystems, speeding up derivative builds and lowering NRE costs.

AUTONOMOUS AND MOBILE PLATFORMS

Unmanned and mobile systems demand compact, configurable cable assemblies and connectors that meet strict SWaP constraints without sacrificing durability.

- **UAV Systems:** Lightweight, high-frequency links maintain stable remote piloting and video transmission.
- **Military Vehicles:** Ruggedized, vibration-resistant connectivity keeps mobile command centers online.

NAVAL AND INFRASTRUCTURE PLATFORMS

Naval and ground-based systems require heavy-duty, corrosion-resistant RF components and integrated EMI protection to survive harsh maritime and outdoor environments.

- **Naval Communications:** Sealed, corrosion-resistant RF components secure ship-to-shore data transfer.
- **Ground-Based Radar:** High-power, thermally stable interconnects allow for continuous, accurate tracking.
- **High-Frequency Antenna Systems:** Low-loss RF paths preserve signal integrity over long distances.

VALIDATION SYSTEMS

Evaluating advanced platforms, such as SATCOM, phased array radar and missile systems, pushes RF infrastructure to its limits and helps confirm mission readiness before deployment.

- **Test and Measurement:** Precision RF connectors and matched attenuators maintain accurate, repeatable measurements at frequencies above 65 GHz.



MOLEX RF SOLUTIONS FOR AEROSPACE AND DEFENSE

Molex offers an extensive portfolio of connectors, passive components and EMI filters engineered to address the diverse demands of modern aerospace and defense architectures. These solutions prioritize signal integrity, thermal management and ruggedization to meet today's stringent MIL-SPEC and DO-160 standards. By moving from piece-part sourcing to pre-validated subsystems, engineering teams can reduce integration risk and accelerate time-to-field.

RF Interconnect Solutions

Increasingly complex aerospace and defense systems require reliable RF performance without compromising space or weight. Molex delivers high-performance, standards-aligned RF connectivity through its portfolio of Precision RF Connectors that includes SMA, TNC, SMP and SMPM options.

	Frequency Range	VSWR	Insertion Loss	Voltage	Insulation Resistance	Dielectric Withstanding Voltage	Mating Cycles	Operating Temperatures	Material
SMA									
	DC to 18 GHz	1.10 + 0.0045 f(GHz)	0.03 √(f(GHz)) dB max.	500V AC (RMS) max. at sea level	≥5,000 Megohms	1,000V AC (RMS)	500 min.	-65 to +165°C	Coupling nut and body: passivated stainless steel Center contact: 30 µinch gold
TNC									
	DC to 11 GHz	1.3:1 max.	0.3 dB max.	500V AC (RMS) max. at sea level 125V AC (RMS) max. at 70,000 feet	≤5,000 Megohms	1,500V AC (RMS)	500 min.	-65 to +165°C	Coupling nut and body: passivated stainless steel Center contact: 30 µinch gold

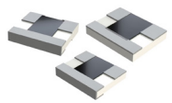
	Frequency Range	VSWR	Insertion Loss	Voltage	Insulation Resistance	Contact Resistance	Mating Cycles	Operating Temperatures	Material
SMP									
	DC to 40 GHz	1.7:1 (-12 dB) max.	0.1 √(f(GHz)) dB max.	335V AC (RMS) max. continuous	5,000 Megohms min.	6 milliohms max.	Full detent: 100 min. Smooth bore: 500 min.	-65 to +165°C	Body: brass or beryllium copper Center contact: 30 µinch gold
SMPM									
	DC to 65 GHz	1.35:1 (-16 dB) max.	0.1 √(f(GHz)) dB max.	325V AC (RMS) max. continuous	5,000 Megohms min.	6 milliohms max.	Full detent: 100 min. Smooth bore: 500 min.	-65 to +165°C	Body: brass or beryllium copper Center contact: 30 µinch gold

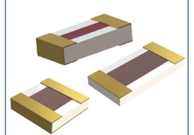
RF Signal Conditioning and Power Management Solutions

Complex RF systems often struggle with thermal hotspots and signal instability under high power loads. Molex RF signal conditioning and power management solutions, including coaxial attenuators, coaxial terminations, chip attenuators and surface mount terminations (SMTs), maintain predictable performance and power handling in these demanding environments.

	Frequency Range	VSWR	Input Power	Attenuation Accuracy	Coaxial Connector	Configuration	Connector Length	Operating Temperatures	Material
RF Coaxial Attenuators									
	DC to 50 GHz	1.75:1 max.	0.5W @ +25°C 1W @ +25°C Derated linearity to 0.1W @ +85°C	3, 6 and 10 dB: ±1.5 dB 20 and 30 dB: ±2.0 dB	2.4mm	Male/female Mates with 1.85 and 2.4mm	1.12" ±0.05" (28.45 ±1.30mm)	-45 to +85°C	Housing: gold -plated beryllium copper Conductor: gold-plated beryllium copper
	DC to 50 GHz	1.75:1 max.	2W @ +25°C Derated linearity to 0.75W @ +55°C	3, 6 and 10 dB: ±1.5 dB 20 and 30 dB: ±2.0 dB	1.85mm	Male/female Mates with 1.85 and 2.4mm	1.12" ±0.05" (28.45 ±1.30mm)	0 to +55°C	Housing: passivated stainless steel Conductor: gold-plated beryllium copper
	DC to 40 GHz	1.40:1 max.	0.5W @ +25°C Derated linearity to 0.1W @ +125°C	3 and 6 dB: ±0.8 dB 10, 20 and 30 dB: ±1.0 dB	2.92mm	Male/female Mates with SMA and 3.50mm	0.88" ±0.05" (22.40 ±1.30mm)	-65 to +125°C	Housing: passivated stainless steel Conductor: gold-plated beryllium copper
	DC to 18 GHz	1.35:1 max.	2W @ +25°C Derated linearity to 0.5W @ +125°C Peak power: 250W (max.)	1 to 6 dB: ±0.3 dB 7 to 20 dB: ±0.5 dB 30 dB: ±0.75 dB	N-type	Male/female Mates with MIL-STD-348	1.76" ±0.03" (44.70 ±0.80mm)	-65 to +125°C	Housing: passivated stainless steel Conductor: gold-plated beryllium copper
	DC to 18 GHz	1.35:1 max.	2W @ +25°C with derated linearity to 0.5W @ +125°C 5W @ +25°C with derated linearity to 1W @ +125°C Peak power: 250W (max.)	0 to 6 dB: ± 0.3 dB 7 to 20 dB: ± 0.5 dB 21 to 30 dB: ± 0.75 dB 31 to 40 dB: ± 1.5 dB	SMA	Male/female Mates with SMA and 3.50mm	0 to 12 dB: 0.86" ±0.03" (21.80 ±0.80mm) 13 to 30 dB: 0.99" ±0.03" (25.80 ±0.80mm) 31 to 40 dB: 1.20" ±0.05" (30.50 ±1.30mm)	-65 to +125°C	Housing: passivated stainless steel Conductor: gold-plated beryllium copper

	Frequency Range	VSWR	Input Power	Coaxial Connector	Configuration	Connector Length	Bead Chain	Operating Temperatures	Physical
RF Coaxial Terminations									
	DC to 50 GHz	DC to 40 GHz: 1.40:1 DC to 50 GHz: 1.60:1	0.5W @ +25°C Derated linearity to 0.1W @ +125°C	2.4mm	Mates with 2.4 and 1.85mm	Male: 0.76” ±0.05” (19.30 ±1.30mm) Female: 0.79” ±0.05” (20.07 ±1.30mm)	Length: 3.5” (89.00mm) Diameter: 0.13” (3.30mm)	-45 to +85°C	Housing and conductor: gold-plated beryllium copper Barrel and coupling nut: passivated stainless steel
	DC to 65 GHz	DC to 10 GHz: 1.20:1 10 to 30 GHz: 1.40:1 30 to 65 GHz: 1.55:1	1W @ +25°C Derated linearity to 0.1W @ +125°C	1.85mm	Mates with 2.4 and 1.85mm	Male: 0.70” ±0.05” (17.78 ±1.30mm) Female: 0.80” ±0.05” (20.32 ±1.30mm)	N/A	-55 to +100°C	Housing: passivated stainless steel Conductor: gold-plated beryllium copper Barrel and coupling nut: passivated stainless steel
	DC to 40 GHz	1.20:1	1W @ +25°C Derated linearity to 0W @ +125°C	2.92mm (SMK)	Mates with SMA, K and 3.50mm	Male: 0.58" ±0.05" (14.70 ±1.30mm) Female: 0.62" ±0.05" (15.70 ±1.30mm)	Length: 3.5" (89.00mm) Diameter: 0.13" (3.30mm)	-55 to +125°C	Housing and bead chain: passivated stainless steel Conductor: gold-plated beryllium copper
	DC to 18 GHz	DC to 4 GHz: 1.10:1 4 to 8 GHz: 1.15:1 8 to 12.4 GHz: 1.20:1 12.4 to 18 GHz: 1.25:1	2W @ +25°C Derated linearity to 1W @ +125°C	N-type	Mates with MIL-STD-348	Male: 1.17" ±0.05" (29.70 ±1.30mm) Female: 1.26" ±0.05" (32.00 ±1.30mm)	Length: 3.5" (89.00mm) Diameter: 0.13" (3.30mm)	-65 to +125°C	Housing and bead chain: passivated stainless steel Conductor: gold-plated beryllium copper
	DC to 26.5 GHz	DC to 4 GHz: 1.05:1 4 to 8 GHz: 1.10:1 8 to 12.4 GHz: 1.15:1 12.4 to 18 GHz: 1.20:1 18 to 26.5 GHz: 1.35:1	1W @ +25°C Derated linearity to 0W @ +125°C	SMA	Mates with MIL-STD-348	Male: 0.42" ±0.05" (10.70 ±1.30mm) Female: 0.54" ±0.05" (13.70 ±1.30mm)	Length: 3.5” (89.00mm) Diameter: 0.13” (3.30mm)	-65 to +125°C Temperature coefficient: ±250 ppm/°C	Housing and bead chain: passivated stainless steel Conductor: gold-plated beryllium copper or brass

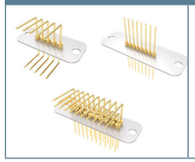
	Frequency Range	VSWR	Power Handling	Attenuation Range	Impedance	Operating Temperatures	Material
Chip Attenuators							
	DC to 18 GHz	1.25:1 to 1.50:1	0.15 to 5W	1 to 20 dB selectable, up to 30 dB on request	50 Ohms	-55 to +150°C	Substrate: high-purity alumina ceramic Finish: silver or tin-lead solder

	Frequency Range	VSWR	Power	Width	Length	Height	Impedance	Operating Temperatures	Material
Surface-Mount Terminations									
	DC to 12.4 GHz	1.25:1	10W max. (DC to 4 GHz) 5W max. (DC to 10 GHz) 3W max. (DC to 12.4 GHz)	DC to 4 GHz, DC to 10 GHz: 0.05" (1.30mm) DC to 12.4 GHz: 0.025" (0.65mm)	0.05" (1.30mm)	0.01" (0.25mm)	50 and 100 ±2 Ohms	-55 to +125°C	Substrate: beryllium oxide ceramic, alumina or alumina nitride Resistor: thin-film tantalum nitride Terminal: gold-plated or tin lead solder

EMI/EMC Protection and Signal Integrity Solutions

High-frequency, mission-critical environments are highly susceptible to disruptive EMI. Molex integrated EMI/EMC protection and signal integrity management solutions, featuring EMI-filtered D-Subs, EMI filter plates and circular EMI filter connectors, help engineers achieve compliance and reliable operation.

	Current	Shell Sizes	Voltage	Capacitance Values	Connector Options	Contact Resistance	Material	Operating Temperatures	Dielectric
EMI-Filtered High-Performance D-Sub Pi Connectors									
	5.0A; RF current: 0.3A	9, 15, 25, 37, 50	100V max.	100 to 4,000 pF	Threaded locking inserts Grounding bracket Grounding bracket with board lock	10 milliohms max.	Grounding springs: beryllium copper, tin plated per MIL-T-10727	-55 to +125°C	150V and 300V
EMI-Filtered High-Performance D-Sub High-Density Connectors									
	3.0A; RF current: 0.3A	15, 26, 44	100V max.	85 to 4,000 pF	Threaded locking Inserts #4-40 UNC or metric M3.0 threaded inserts in mounting flanges	15 milliohms max.	Metal bracket in place of plastic Grounding springs: beryllium copper, tin plated per MIL-T-10727	-55 to +125°C	300V

	Frequency Range	Filter Circuit	Lines	Lead Configuration	Lead Diameter	Base Plate Thickness	Voltage	Attachment	Operating Temperatures	Material
EMI Filter Plates										
	5 MHz to 18 GHz	C, Pi	3 to 50	Vertical, right angle	0.025" (0.64mm) for 0.100" (2.54mm) centers, 0.020" (0.51mm) for 0.079" (2.00mm) centers	0.012" (0.30mm)	100V	Snap-in (5 MHz to 18 GHz) or bolt-in (5 MHz to 1 GHz)	-55 to +125°C	Base plate: brass UNS C26000/C27000 (bolt-in) or beryllium copper (snap-in) Lead material: copper alloy Plating: tin or silver (base plate); gold (leads)

	Capacitance Values	Circuit Types	Capacitance Codes	Shell Sizes	Voltage	Contact Termination Style	Shell Style	Operating Temperatures	Material
Circular EMI Filter Connectors									
	1,000 to 50,000 pF (custom values and tolerances available)	C, Pi	102, 103, 252, 253, 503	9, 11, 13, 15, 17, 19, 21, 23, 25	200V DC or 125V AC max.	Pin to PCB, pin to solder cup, socket to PCB, socket to solder cup	Wall mount, jam-nut mount	-55 to +125°C	Finish: electroless nickel, olive drab cadmium, black nickel zinc, nickel Teflon Shell material: stainless steel, aluminum, composite

AEROSPACE AND DEFENSE RF SOLUTION SELECTION GUIDE

Navigating complex RF architectures requires aligning the right interconnects, passives and EMI filters to specific mission profiles. Use the following selection matrix to quickly identify recommended Molex RF solutions based on platform requirements and operating environments.

Products / Applications	Missile Defense Systems	Tactical Weapons	Radar Communication Systems	Satellite Communication Systems	Airborne Radios	Military Radios	Instrumentation Systems	High-Frequency Antennas	Electronic Engagement Systems	Military and Commercial Aircraft	Global Positioning System (GPS) Devices	Unmanned Aerial Vehicle (UAV) Flight Controls	Military Vehicles	Night Vision Sensors
SMA Connector		•	•	•	•	•		•		•	•			•
TNC Connector	•	•	•	•	•	•			•		•		•	•
SMP Connector			•	•		•	•	•						
SMPM Connector			•	•		•	•	•						
Coaxial Attenuator	•	•	•	•		•			•	•	•			
Coaxial Terminator	•	•	•	•		•			•	•	•			
Chip Attenuator	•		•						•	•				
Chip Termination	•		•						•	•				
EMI Filtered D-Sub		•			•				•	•		•		•
EMI Filtered D-Sub High-Density		•			•				•	•		•		•
EMI Filter Plate		•							•	•				•
Circular EMI Filter Connectors	•		•			•			•	•		•	•	

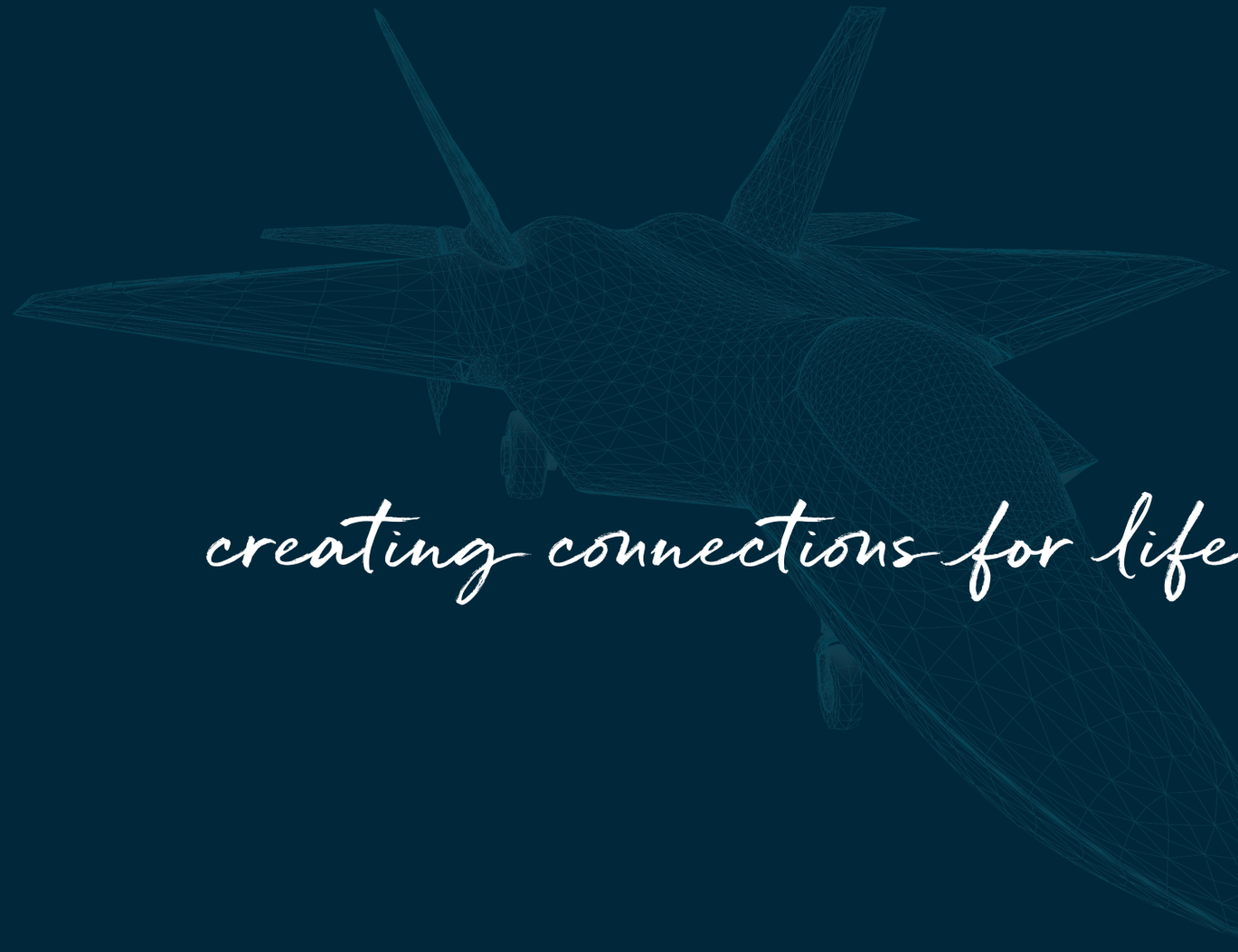
ADVANCING THE NEXT GENERATION OF AEROSPACE AND DEFENSE RF SYSTEMS

The Molex Precision RF Connectors portfolio delivers predictable high-frequency performance, robust power management and integrated EMI/EMC protection. Designed for mission-critical environments, these solutions support the development of advanced aviation radar, secure military communications and next-generation UAV platforms.

Treating connectivity as a strategic design input empowers engineering teams to accelerate qualification cycles, reduce integration rework and improve overall mission reliability. By helping customers overcome complex RF integration challenges, Molex plays a vital role in advancing aerospace and defense innovation.

Explore the complete **Molex Aerospace and Defense RF Solutions portfolio.**





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